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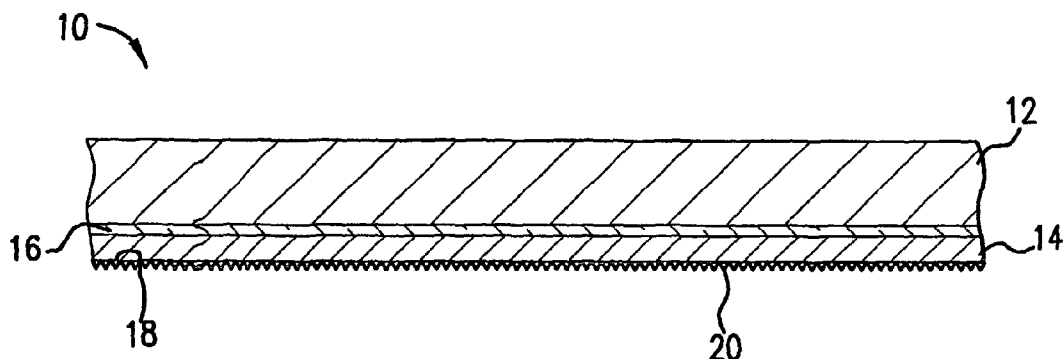
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(54) Title: COPPER FOIL WITH LOW PROFILE BOND ENHANCEMENT



(57) Abstract: A composite material (10), comprising a carrier strip (12), the carrier strip (12) comprising a first side, the first side comprising a substantially uniform roughness, an electrolytically deposited copper foil layer (14) having opposing first and second sides and a thickness of from 0.1 micron to 15 microns. The entire copper foil layer (14) thickness having been deposited from a copper containing alkaline electrolyte, and a release layer (16) effective to facilitate separation of the copper foil layer (14) from the carrier strip (12) disposed between and contacting both the first side of the carrier strip (12) and the second side of the copper foil layer (14).



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